

Amendments to the Specification:

On page 1 of the Specification, please amend Paragraph 1 as follows:

The present application **is a divisional of U.S. Application Serial No. 10/103,048 entitled SEMICONDUCTOR PACKAGE AND METHOD FOR MANUFACTURING THE SAME filed March 21, 2002, which** claims priority to Korean Patent Application No. 2001-15991 entitled SEMICONDUCTOR PACKAGE AND METHOD FOR MANUFACTURING THE SAME filed March 27, 2001.